CELCON® LW90FS-K

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Celcon® acetal copolymer grade LW90FS-K is a wear resistant medium flow grade containing silicone and a high level of PTFE to give excellent slip and wear resistance properties in demanding applications.

Product information

Resin Identification	POM-S18	ISO 1043
Part Marking Code	>POM-S18<	ISO 11469

Rheological properties

Melt volume-flow rate	8	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	0.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.1	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2100	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	44	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	17	%	ISO 527-1/-2
Flexural modulus	2050	MPa	ISO 178
Charpy impact strength, 23°C	61	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	4	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	4.4	kJ/m^2	ISO 180/1A
Poisson's ratio	0.4[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	87	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120	E-6/K	ISO 11359-1/-2

Physical/Other properties

Density	1510	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C

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Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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